

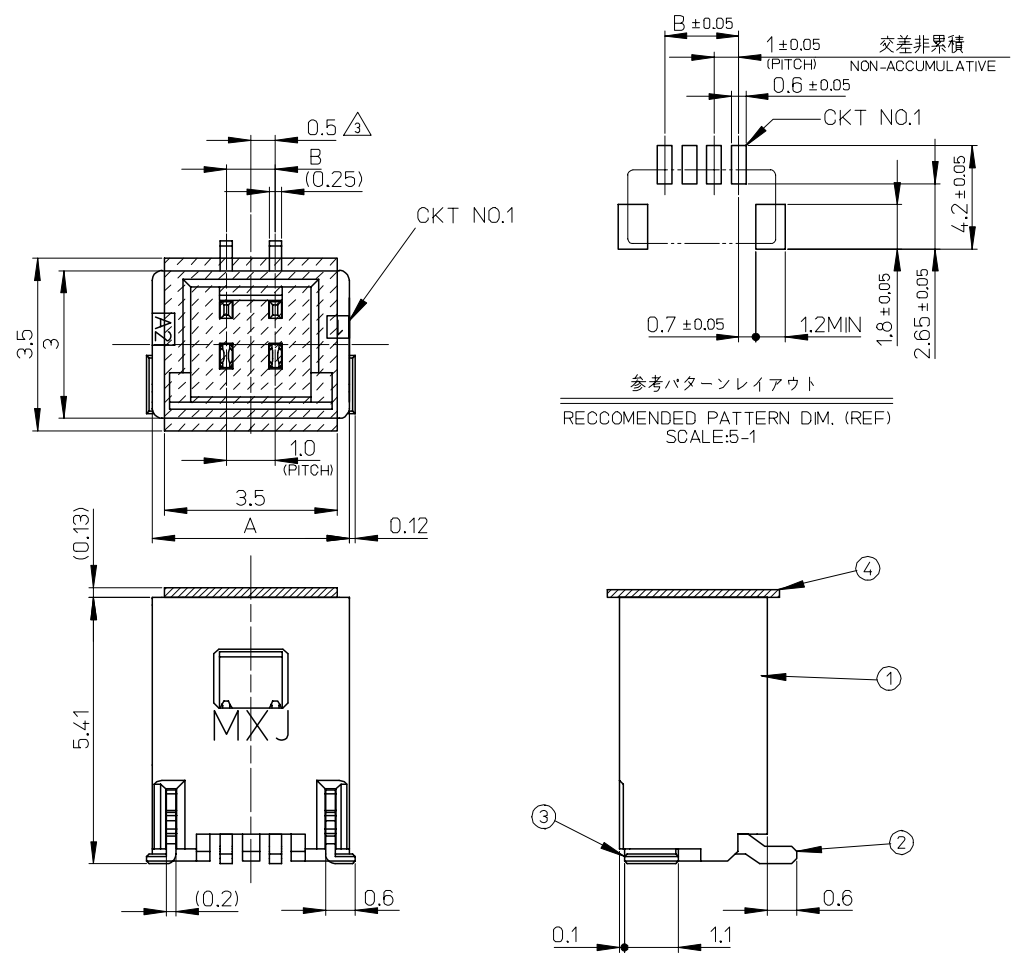
番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	46ナイロン UL94V-0 色:自然色 46 NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

1. 嵌合相手: 501330-****
MATE WITH: 501330-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極については、SD-501331-002を参照下さい。
REFER TO SD-501331-002 ABOUT 6-15CKT.
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

※対応可能な極数は、別途お問い合わせ下さい。

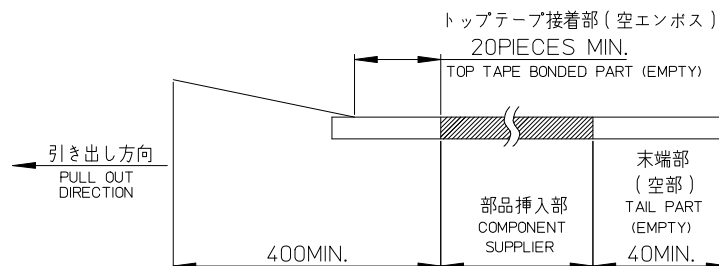
4.0	7.0	501331-0509	5	501331-**09
3.0	6.0	501331-0409	4	
2.0	5.0	501331-0309	3	
1.0	4.0	501331-0209	2	
B	A	MATERIAL NO.	CKT.	MODEL NO.



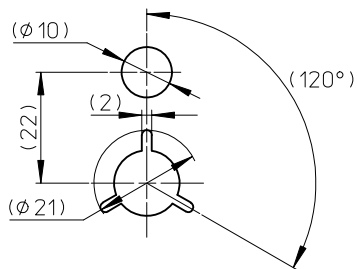
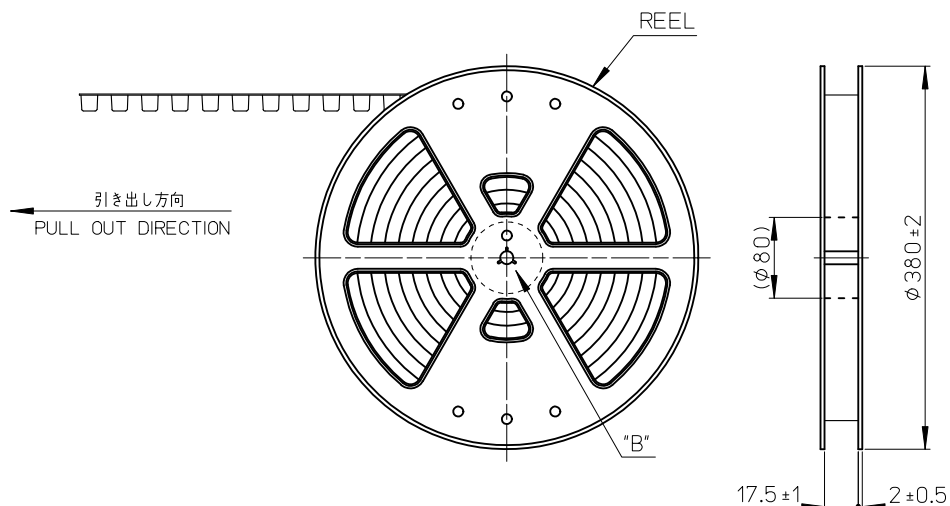
REVISED EC NO: J2007-2540 DRWN: A0YAGI CHKD: YMAEDA APPR: NUKITA	DESCRIPTION 2007/03/13 2007/03/13 2007/03/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2004/07/30	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT		MOLEX INCORPORATED	
10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2004/07/30	APPROVED BY MIYAZAWA		DATE 2004/07/30	DOCUMENT NO. SD-501331-001		
30 OVER	± 0.3	ANGULAR ± 3 °		MATERIAL NO.		SEE TABLE			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量: 1100個/リール
NUMBER OF CONNECTORS: 1100PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

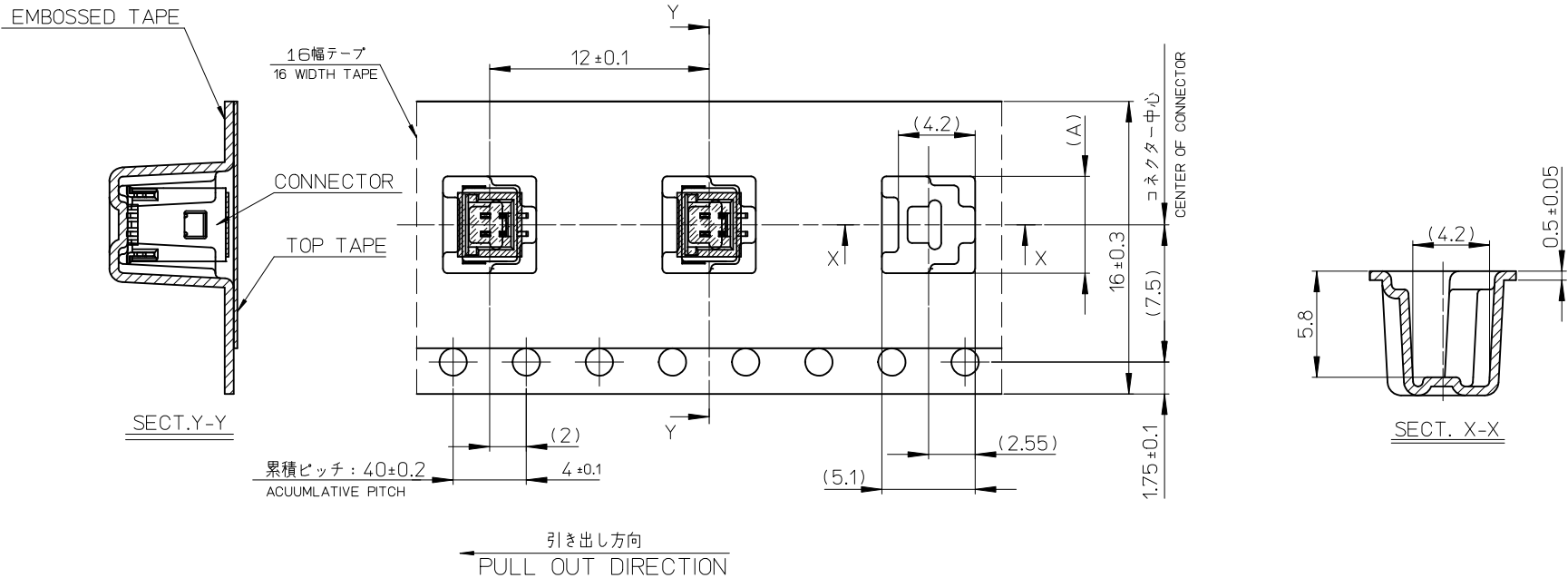


4. 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET、PE、REF
TOP TAPE
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(501331-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 501331-0607~1507)



DETAIL "B"

REVISED EC NO: J2010-0951 2009/12/16 DRWN: NITO CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE SHEET 2				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-501331-003		SHEET NO. 1 OF 2				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



8.3	501331-0509	501331-0507	5	501331-***7
7.3	501331-0409	501331-0407	4	
6.3	501331-0309	501331-0307	3	
5.3	501331-0209	501331-0207	2	
(A)	CONNECTOR	MATERIAL NO.	CKT.	MODEL NO.

REVISED EC NO: J2010-0951 DRWN: NITO 2009/12/16 CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	± 0.25	NYOSHIDA	2005/01/18	1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	30 OVER	± 0.3	CHECKED BY	DATE			
ANGULAR ± 1 °		APPROVED BY	DATE	MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANODA	2005/01/18	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501331-003	SHEET NO. 2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							